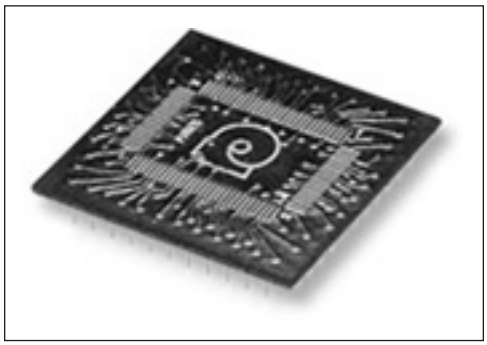
P/N 96-160M65 160-Position, 0.0256 [0.65] Pitch QFP-to-PGA Adapter

FEATURES

- Convert surface-mount QFP packages to a 15x15 PGA footprint.
- Reduce costs by using less-expensive QFP packages to replace PGA footprints in existing designs.
- Pins are mechanically fastened and soldered to board using Aries patented process, creating a reliable electrical connection and rugged contact.
- Consult factory for Panelized Form or for mounting of consigned chips.



GENERAL SPECIFICATIONS

- ADAPTER BODY: FR-4 with 1-oz. Cu traces
- PADS: finished with ENIG (Immersion Au over Electroless Ni)
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: is 200µ [5.08µ] Sn/Pb 93/7 per ASTM B579-73 over 100µ [2.54µ] Ni per SAE AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE**: Aries reserves the right to change product general specifications without notice.

MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71 ±0.08] dia.
- Will plug into standard PGA socket

ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED

ROW-TO-ROW ±0.003 [±0.08]
PIN-TO-PIN ±0.003 [±0.08] NON-CUMULATIVE

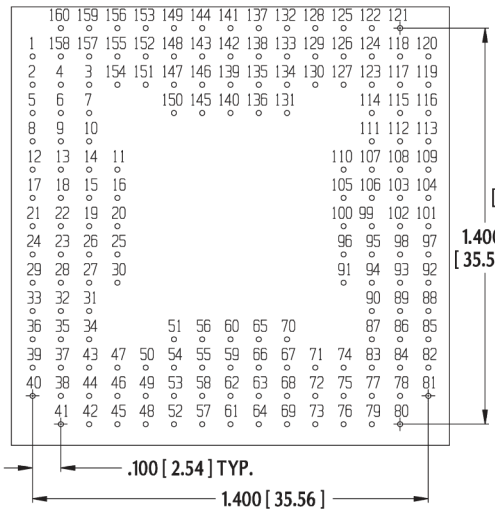
CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS

ORDERING INFORMATION

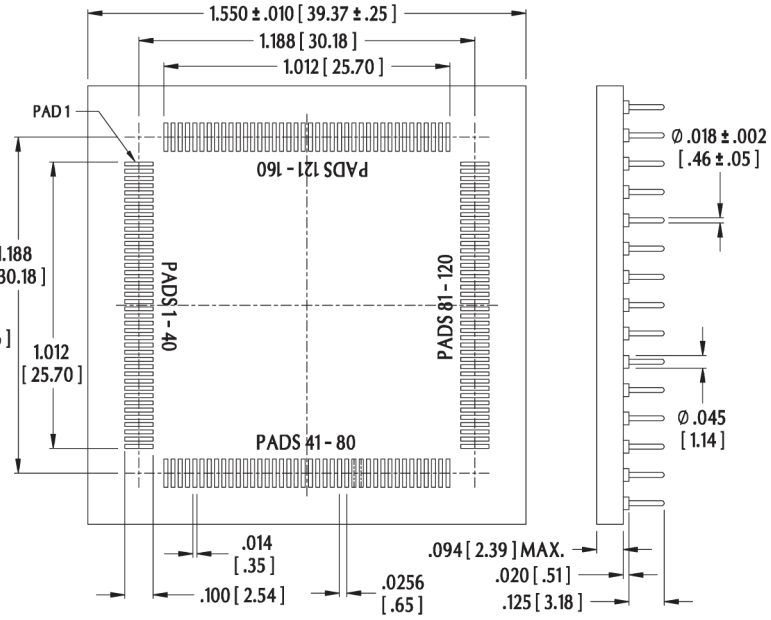
P/N 96-160M65 QFP-to-PGA 15x15 Adaptor

P/N 96-160M65-P QFP-to-PGA 15x15 Panilized Form

P/N 160-PGM15043-30 QFP-to-PGA 15x15 Wire Wrap



X-RAY VIEW TOP SIDE
QFP PAD ASSIGNMENT



TOP (QFP) SIDE

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